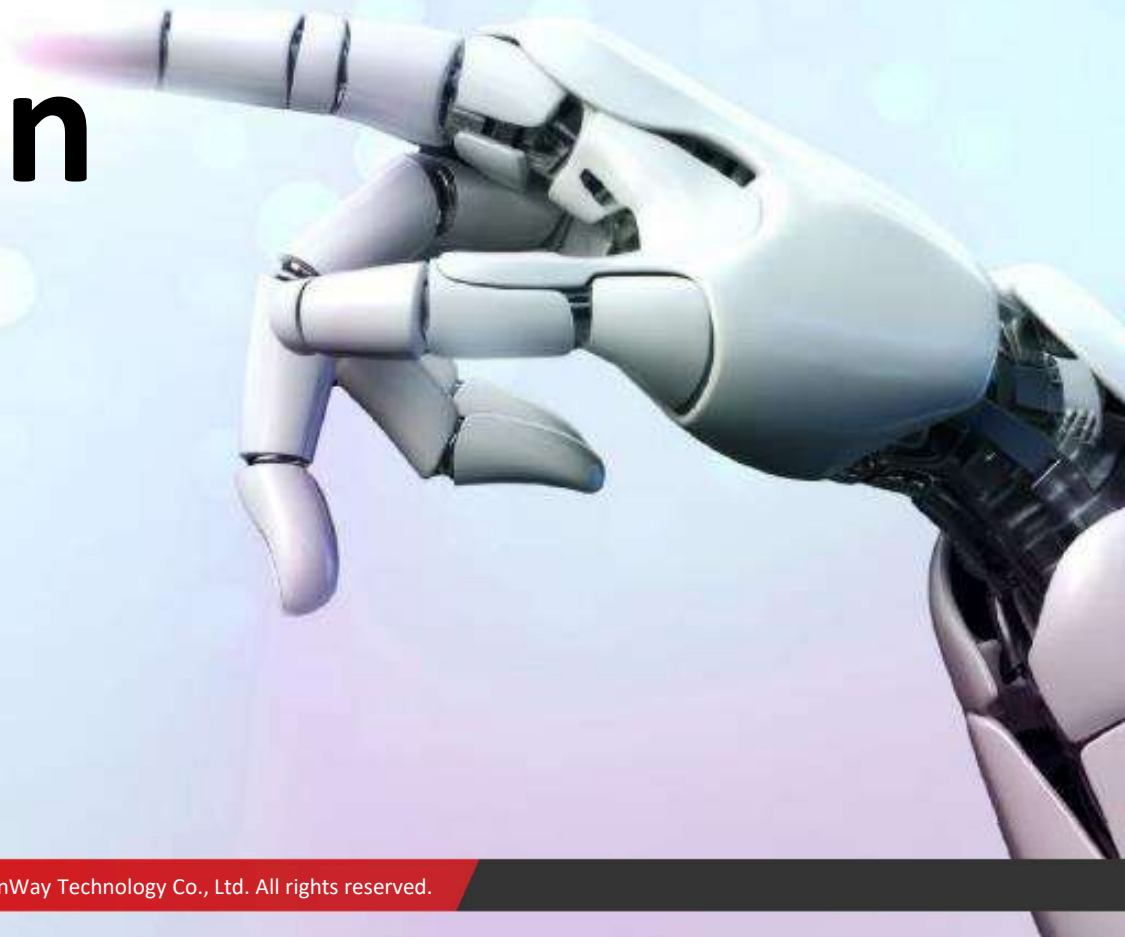




TWSE: 6515

Investor Presentation

2024.10.21



Safe Harbor Notice

This presentation may contain forward-looking statements. All statements, other than statements of historical facts, that address activities, events or developments that WinWay Technology Co., Ltd. expects or anticipates will or may occur in the future (including but not limited to projections, targets, estimates and business plans) are forward-looking statements.

WinWay's actual results or developments may differ materially from those indicated by these forward-looking statements as a result of various factors and uncertainties, including but not limited to market demand, price fluctuations, competition, change in legal, government policies, financial market conditions, and other risks and factors beyond our control.

This presentation does not undertake any obligation to publicly update any forward-looking statements to reflect events or circumstances after the date on which any such statement is made or to reflect the occurrence of unanticipated events.

Company Information



Kaohsiung Headquarter



Hsinchu Branch Office

Founded

2001 / 4 / 10

Business Operation

Design, manufacture, sale and service of test interface products

Chairman & CEO

Mark Wang

Capital Stock

NTD 347,691,200

Employees

919

Registered Address

No.68, Chuangyi S. Rd, Nanzi Dist.
Kaohsiung City, Taiwan

Agenda



Global Presence

Industry Trend

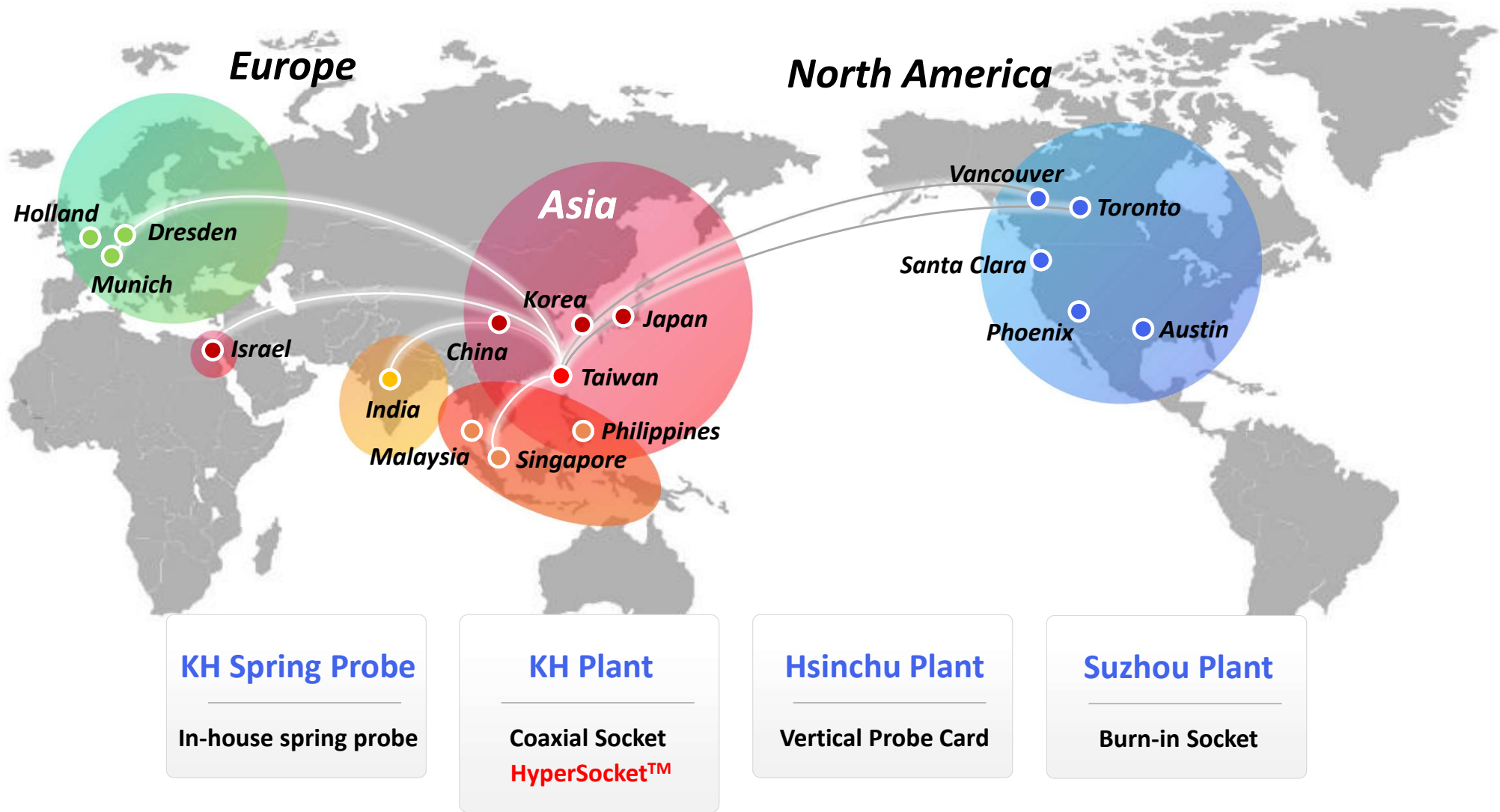
Financial Performance

R&D Innovation

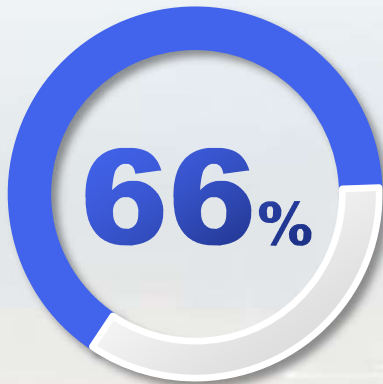
01

Global Presence

Global Service & Support Network



Worldwide Customer



North America



CN



TW



Others

83% Top10 Customers

AI

AP

HPC

CPU

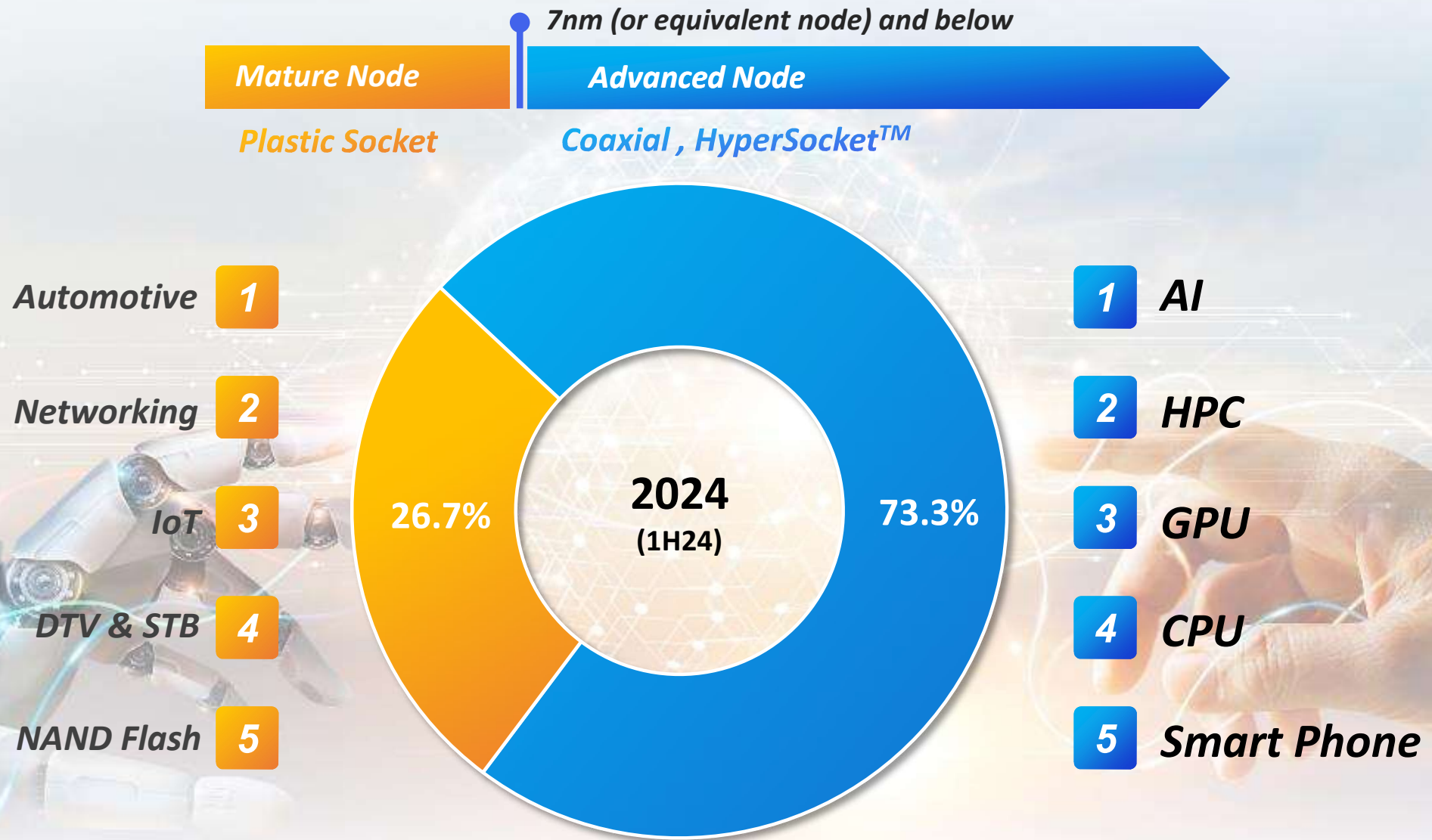
IP Design

GPU

200+ Active Customers

- IC Design
- IDM
- CSP
- ASIC
- Foundry
- OSAT

Bolstered by Advanced Technology



02

Industry Trend

Driving Force for AI



Data Center



AI Server



**High Speed
Networking**

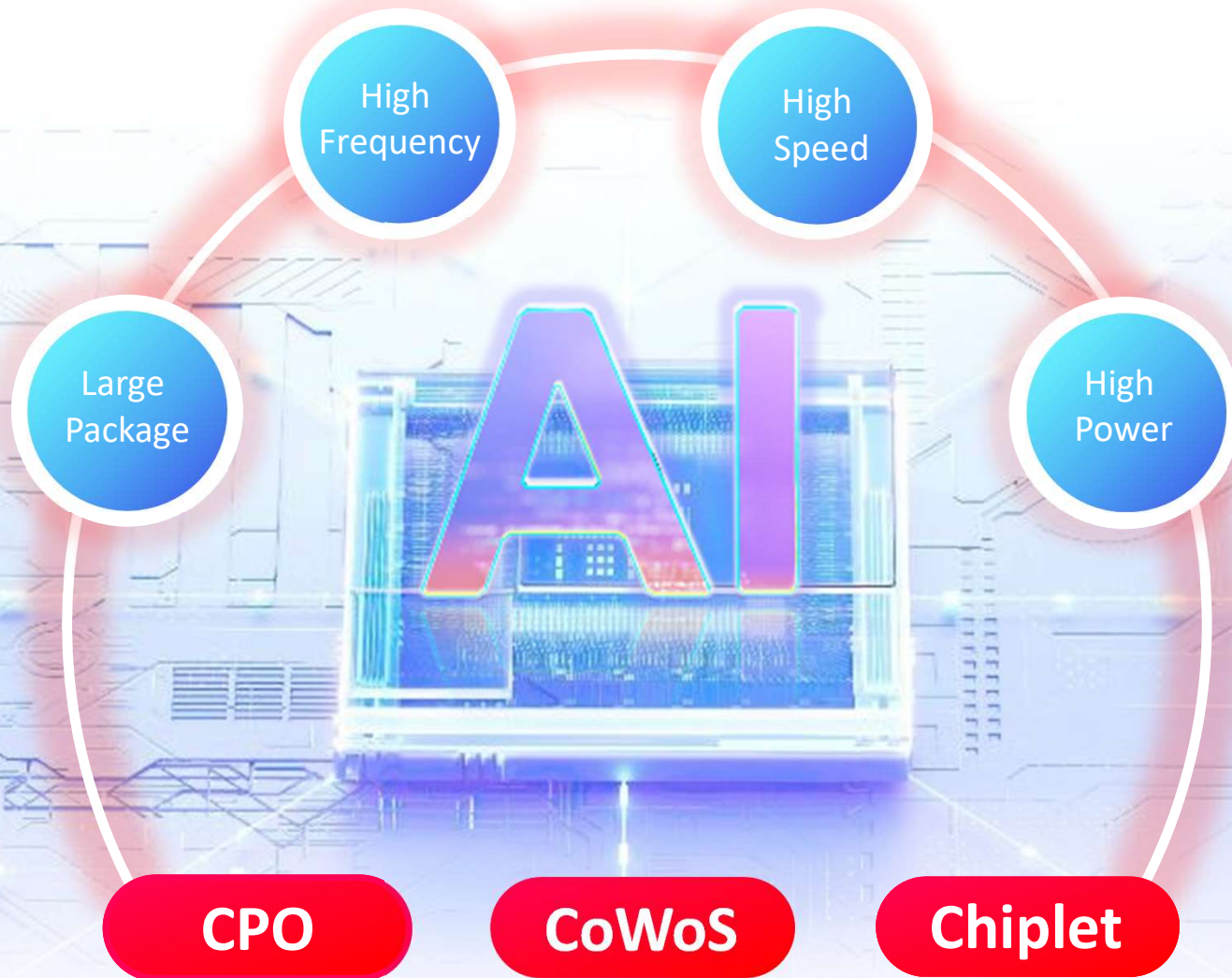


**6G Low Earth
Orbit Satellite**



**AI PC & Phone
NPU&Edge Computing**

High Performance Testing Driven by Advanced Packaging



Opportunities for Semi Test Interface

Wafer Sort & Final Test



Wafer Sort (CP - Circuit Probe)

- ATE , Prober
- VPC PH
- WLCSP PC
- Load Board
- K.G.D
- CoWoS
- Chiplet
- CPO

FT (Final Test)

- ATE , Handler
- Coaxial Socket
- Plastic Socket
- Load Board
- QFP , QFN
- Flip Chip
- Package Device

DFT | Design For Testing

DFM | Design For Manufacturing

Opportunities for Semi Test Interface

SLT, SFT & Burn-in

SLT&SFT Handler



Burn-in Oven



SLT (System Level Test) , SFT

Burn-In

- **HyperSocket™**
- Coaxial Socket
- System Board
- Interposer
- CoWoS
- Chiplet
- SiP
- Package Device

- HP BI Oven
- BI Socket
- BI Board
- Reliability BI (Static)
- Dynamic BI
- **SLT BI (Behavior)**

DFT

Design For Testing

DFM

Design For Manufacturing

Greater Need for System Level Test

SLT&SFT

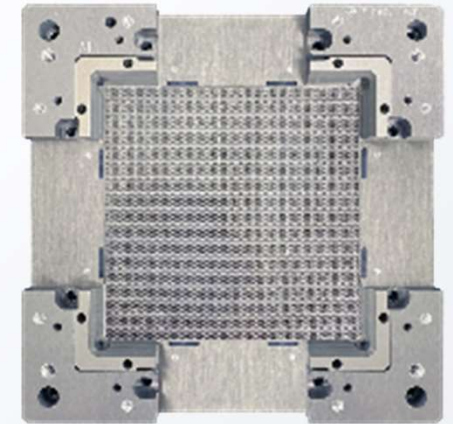
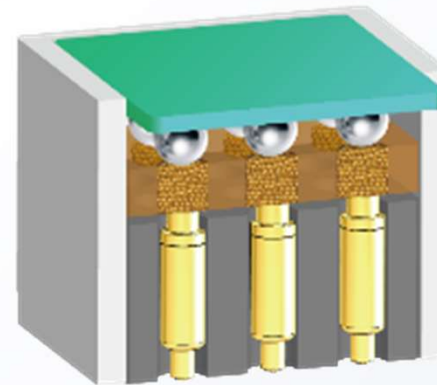
2024-2028 CAGR

More than

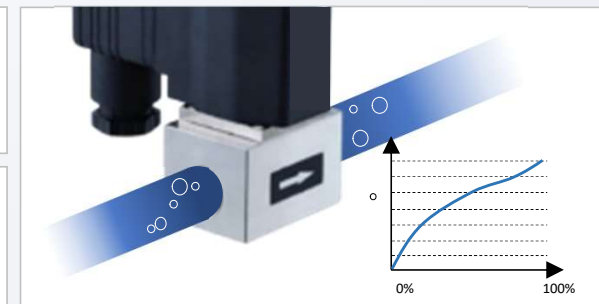
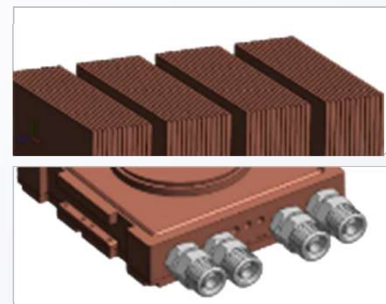
Greater than
industry growth

15% ↑

HyperSocket™



Coaxial Socket



Thermal System (Water Cooling , Liquid Cooling)

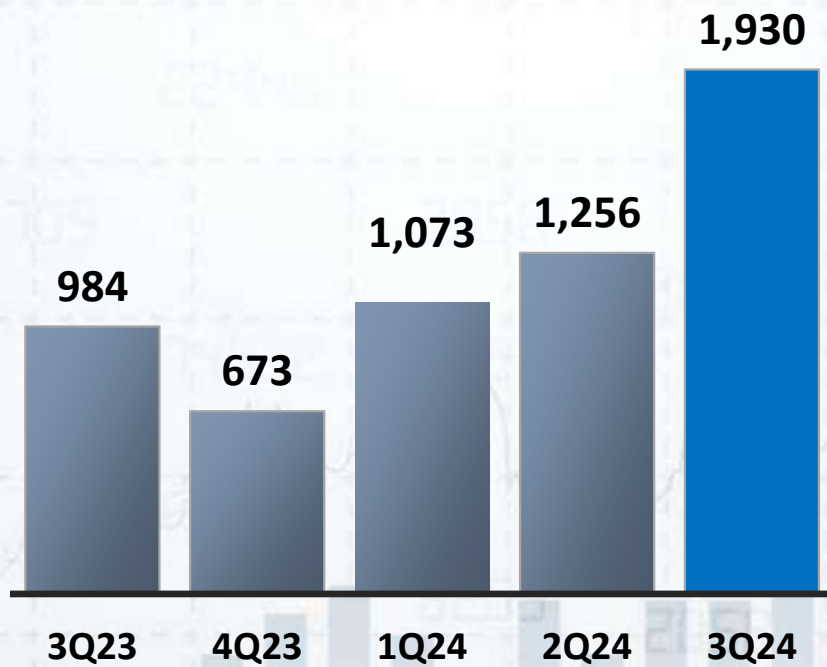
Source: WinWay 2024

03

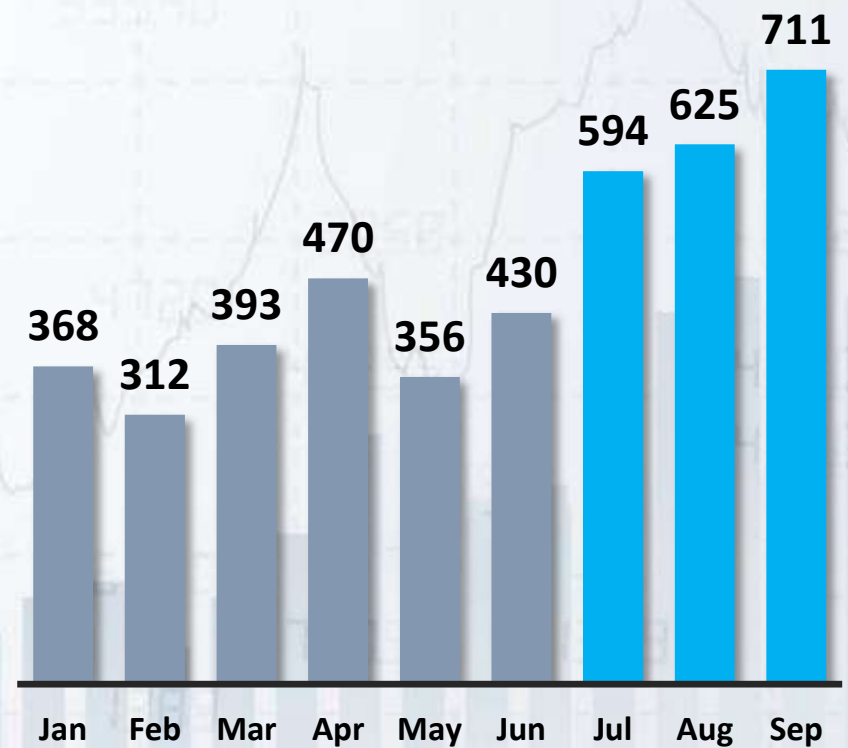
Financial Performance

Revenue Trend

QUARTERLY REVENUE
(NTD MILLION)

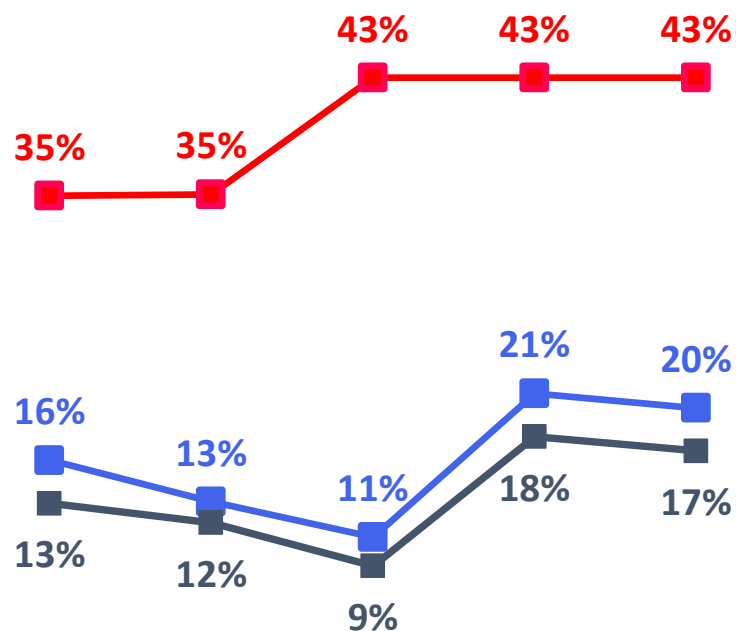


2024
MONTHLY REVENUE
(NTD MILLION)



Profitability Trend

— Gross Margin — Operating Margin — Net Margin



2023 EPS
(NT\$) **13.52**

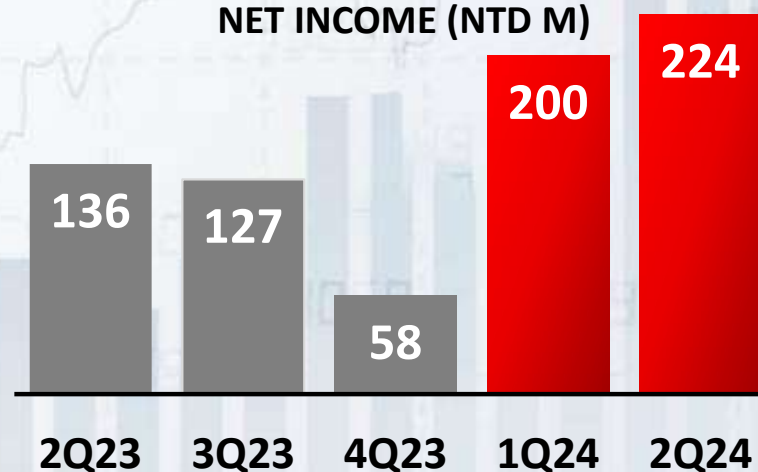
Dividend
11.0

Dividend Payout: 2024.08.15

EPS (NT\$)

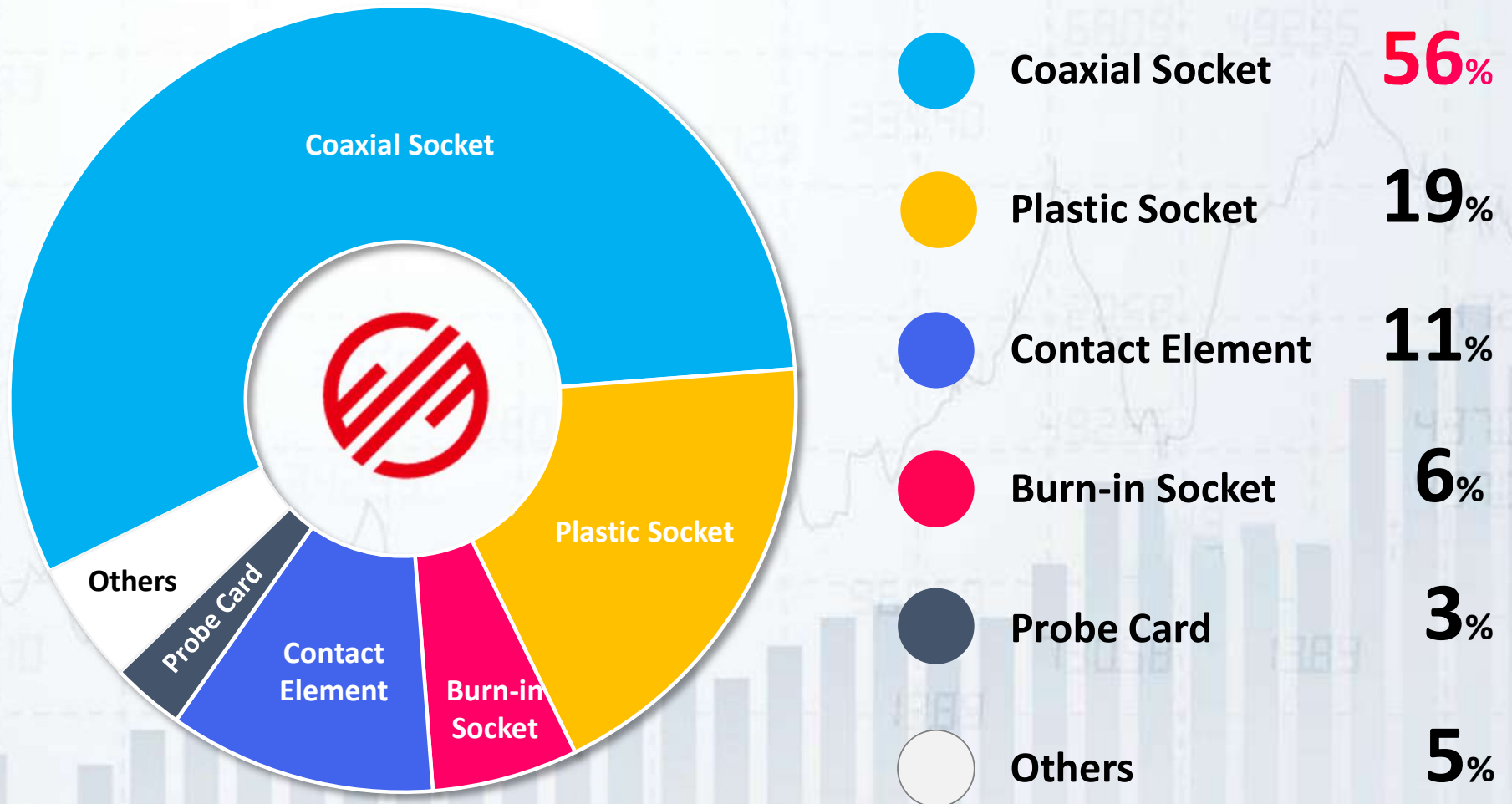
3.96	3.70	1.68	5.81	6.52
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NET INCOME (NTD M)



Revenue by Product Mix

(2024.1H)



Revenue by End Market

END MARKET (2024.1H)

HPC & AI

60% *HyperSocket™, Coaxial*

PC & Gaming

12% *HyperSocket™, Coaxial*

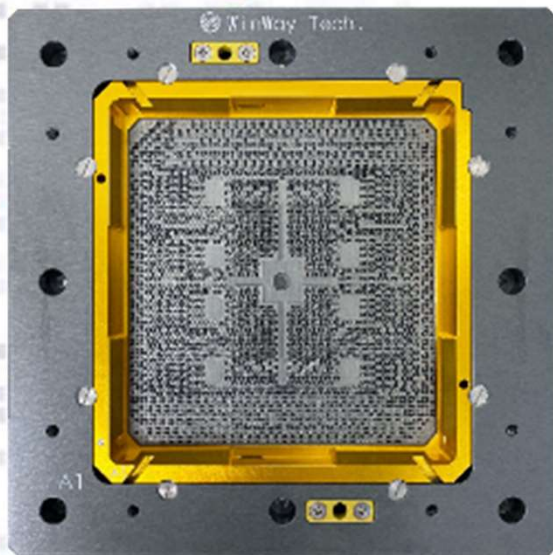
Smartphone

11% *POP Plastic Socket*

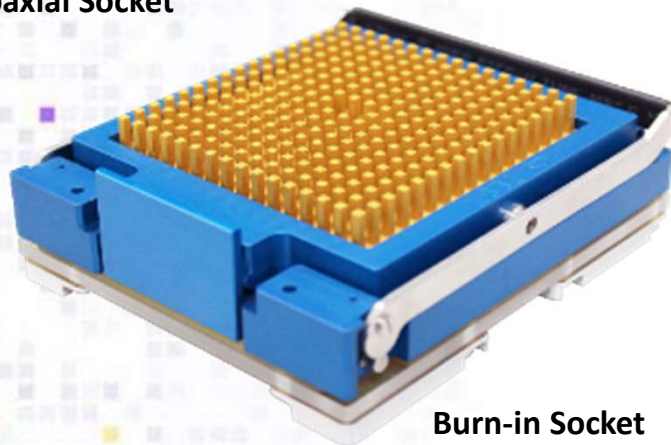
Networking & Others

17% *Plastic Socket*

Semiconductor Test Interface Leadership



Coaxial Socket



Burn-in Socket

2023

**Test Socket
Ranking**

3

2023

**Test and Burn-in
Socket Ranking**

5

2023

**Probe Card
Ranking**

20

Source: Yole Intelligence, 2024/04

04

R&D Innovation

Best-in-Class Test Socket

WinWay HyperSocket™

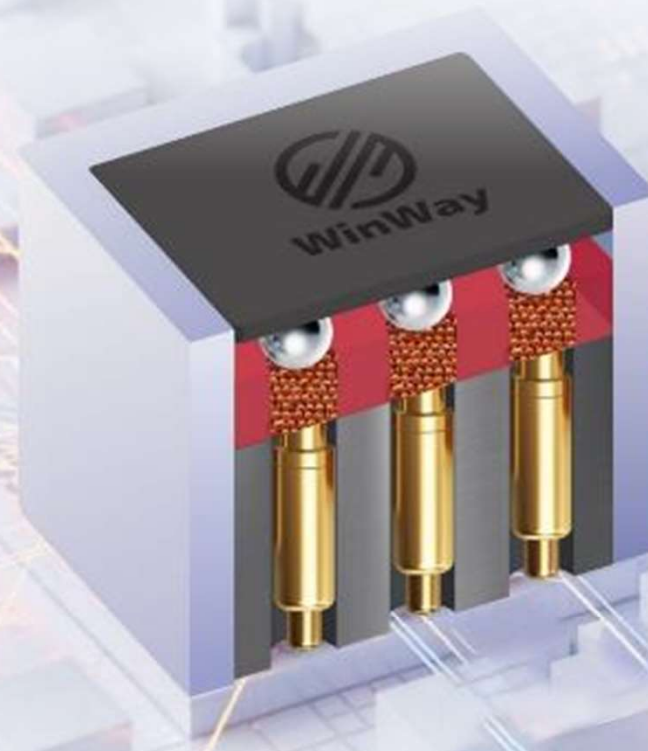
AI , HPC SLT

Smartphone SFT

Automotive Radar

PMIC

WiFi7



Optimal for high-speed testing with outstanding consistency

Excellent thermal dissipation for probes; increased lifespan

Silicon Photonics for Co-Packaged Optics

Unlocking the Future of AI Performance



Coaxial Socket

HyperSocket™

Thermal System

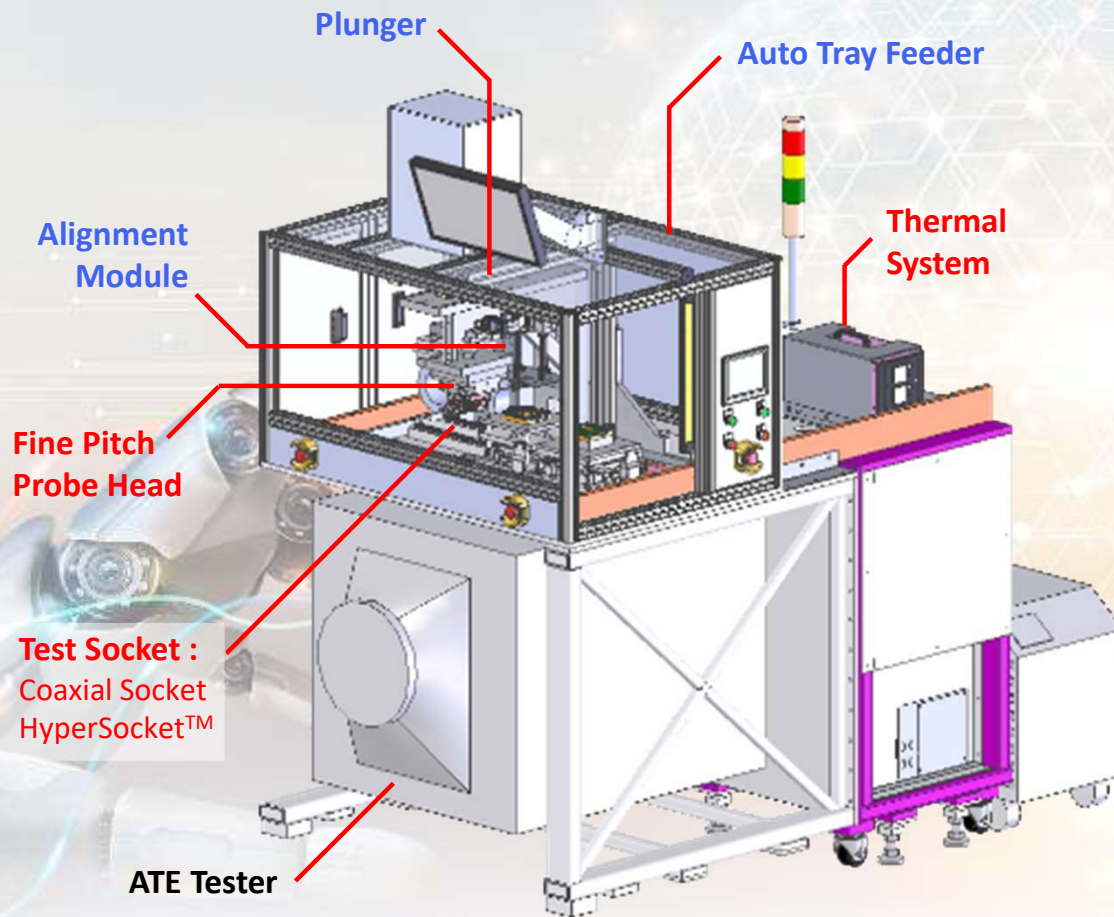
Vertical Probe Card



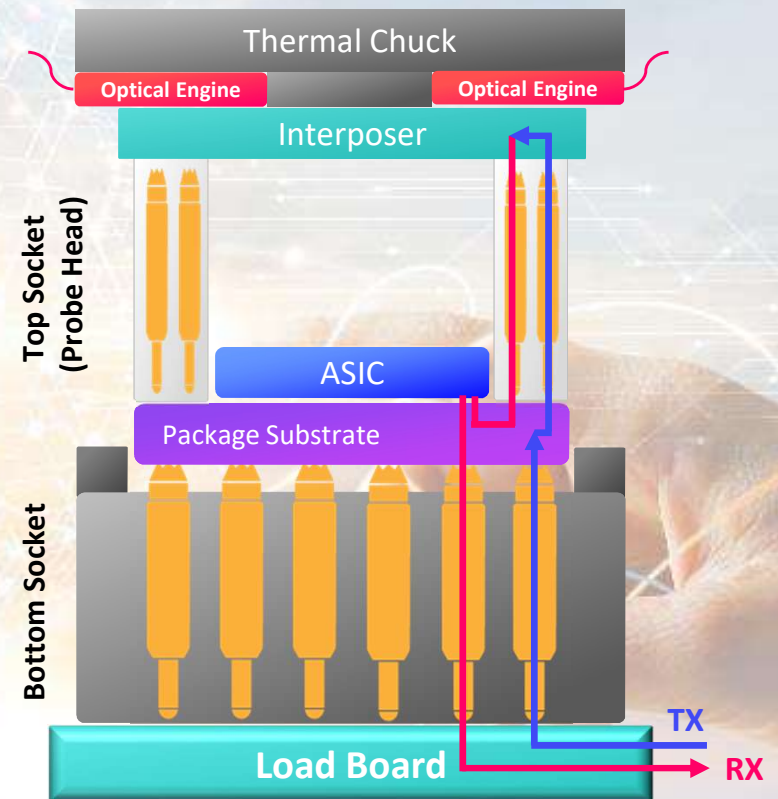
Introducing Wafer-Level CPO Probing Solution

224Gbps Optical Engine Auto Alignment System

Double Sided Probing System



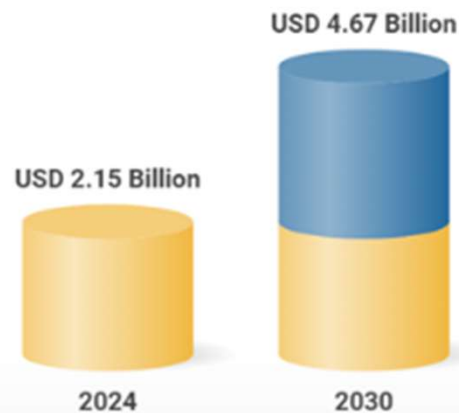
Optical and Electrical Test



CPO Market Opportunities

Global Co-Packaged Optics Market

Market forecast to grow at a CAGR of 13.5%



**CAGR
13.5%**

SOURCE: RESEARCH AND MARKETS Report, 2024

High Data Rate

Lower \$ per Gb/s

Better Reliability

Lower Power Consumption

Optics and ICs are getting closer

Smaller Photonics Components

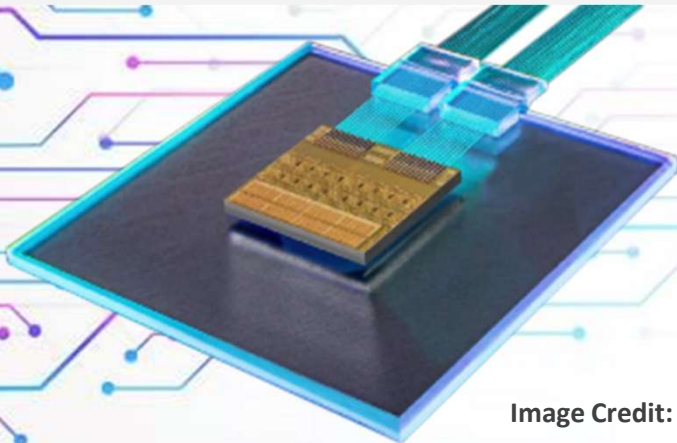


Image Credit: Ayar Labs, 2023

Spring Probe Manufacturing

Socket All in House



2024
Demand **6M** / Month

2024
Capacity **3M** / Month

2024
Output **2M** / Month

Cost Reduction

Customer Growth

THANK YOU

You may contact WinWay Technology via

sales@winwayglobal.com

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www.winwayglobal.com